



HLT3000

Two-part, Dispensable Thermal Gap Filler with High Thermal Conductivity

BENEFIT AND FEATURES

- Modified viscosity and thixotropy properties
- Suitable for dispensing and printing process
- Thin bond line
- Excellent surface wetting
- Proven long term reliability

OVERVIEW

Honeywell HLT3000 is two-part, dispensable thermal gap filler with low viscosity and good thixotropy properties. The gap filler is silicone based, it is easy to dispense and print after 1:1 mixing. It is formulated to balance thermal performance, phase separation and long term reliability. With its high compressibility, it is designed to minimize thermal resistance at interfaces and suitable for thin bond line applications. The material is available in 200+200cc syringes, 1+1 gallon and 5+5 gallon jars.

TYPICAL APPLICATIONS

- EV battery package
- Automotive electronics
- Telecommunications
- LED lighting
- Consumer electronics

STORAGE & USE

- Shelf Life 6 months at 23±2°C

Property	HLT3000	Test Method
Specific Gravity	3.1	ASTM D792
Viscosity (cps@25°C)	100,000-200,000	ASTM D2196 (Brookfield Viscometer, #7 spindle, 10rpm)
Hardness (Shore00)	50	ASTM D2240
Thermal Conductivity (W/m-K)	3.0	ASTM D5470
Dielectric Strength (KV/mm)	>10	ASTM D149
Volume Resistivity(Ω-cm)	>1.0×10 ¹³	ASTM D257
BLT(mm)	0.05	-
Cure Schedule	25°C (hr)	18
	120°C (min)	20
Pot Life	25°C (min)	>60
Color	White/Blue	Visual

Honeywell Electronic Materials

USA: 1-509-252-2102
 China: 400-840-2233
 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
 Singapore: 65-6580-3593
www.electronicmaterials.com

Although all statements and information contained herein are believed to be accurate and reliable, they are presented without guarantee or warranty of any kind, express or implied. Information provided herein does not relieve the user from the responsibility of carrying out its own tests and experiments, and the user assumes all risks and liability for use of the information and results obtained. Statements or suggestions concerning the use of materials and processes are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should not assume that all toxicity data and safety measures are indicated herein or that other measures may not be required.